

深圳市索瑞达电子有限公司

承 认 书 SPECIFICATION FOR APPROVAL

客 户 名 称 : Customer Name :	立创	
客户料号: Customer P/N:		
产 品 名 称 : Product Name:	功率电感	
索 瑞 达 料 号: Sorede P/N:	SRH.7045.LF101MT00	

制造厂商		
Manuf	acturer	
拟 制	唐杨英	
Draft A	論达电子有個	
审核	21 4 甲藻紀月	
Check	程专用管妃团	
日期		
Date	2022-08-13	

客户承认印章			
Appro	val Signet		
日期 Date			

地址:深圳市观澜镇福城街道新塘村8号源创园陆号A6栋3楼.

Address: 3Rd Floor, Building A6, Yuanchuangyuanlu, No. 8 Xintang Village, Fucheng Street, Guanlan Town, Shenzhen.

电话 Tel: 0755-29803356 传真 Fax: 0755-29803506

电子邮件 E-mail: sorde@vip.163.com

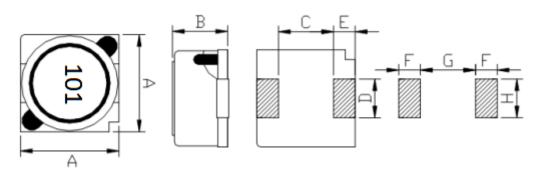
网址 http//www.szsorede.com

修改履历表

Modify Resume

	Modify Resume	
修改日期	修改明细	修改后版本号
Date modified	Modify Details	Version No.
2022-08-13	文件新制订 File formulation	A
2022-00-13	Z Ayripg vi The formulation	

1、外形尺寸 Dimension:



单位Unit: mm

Α	7.0±0.3
В	4.8MAX
С	4.9±0.2
D	2.0 ±0.2
Е	0.9 Ref.
F	1.5 Ref.
G	4.9 Ref.
Н	2.2 Ref.

2、产品品名构成 Product Spec. Model

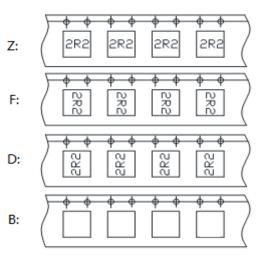
<u>SRH 7045 L F 101 M T 00</u> a b c d e f q h

- a: 系列名称Series name
- b: 产品尺寸Product dimensions (AxBxC)
- c: 密封方式Sealing way (L: 冷封Cold seal Y: 热封Heat seal)
- d: 印字方向 Lettering direction ▶
- e: 电感值Inductance Value

(1R0:1.0uH; 100: 10uH; 101:100uH)

- f: 电感公差Inductance Tolerance (K:10%; M:20%; N:30%)
- g: 包装Package(T:磁带/卷轴Tape/Reel、B: 散装Bulk)
- h: 编号Numbering (标准standard)

► Lettering direction



3、材料清单MATERIAL LIST

NO.	PARTS	MATERIAL	UL FILE NO.	TEMP. CLASS
1	CORE	DR 5.4*4.0 B=2.5 F= 2.6 RI 6.8*3.7*5.8 OR EQUIVALENT	NA	NA
2	WIRE	UEWH/U/G1 P180 OR EQUIVALENT	E258243	180℃
3	ADHESIVE	G500/G9010 OR EQUIVALENT	NA	NA
4	BASE	电木(联丰) OR EQUIVALENT	NA	NA
5	SOLDER	Sn99.3-Cu0.7 OR EQUIVALENT	NA	NA
5		-		

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4、电性能参数表 Electrical Characteristics List

规格型号 Part NO.	电感量 Tolerance(µH)	测试频率 Test Freq. (kHz/v)	直流电阻 DC Max (Ω)	额定电流 (A)
SRH.7045.LF101MT00	100	100/0.25	0.300	0.50

※公差Tolerance: N:±30%、M:±20%、K:±10%.

※工作温度Operating temperature rang: -40 ℃ to +105℃ (Including Self-heating)

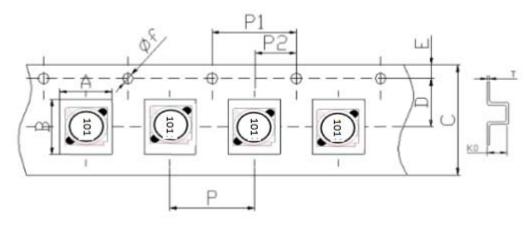
※储存温度Storage termperature rang: -40 ℃ to +105℃

Isat电流:指使电感量比初始值下降10%Max (The rated DC current is that which cause at 10%Max inductance reduction from the initial value)。

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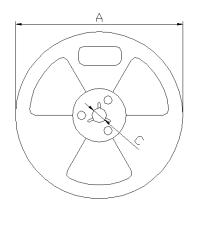
5、产品包装 Packaging

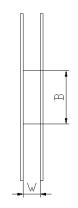
1) 载带包装示意图 Tape packing diagram



Series	Α	В	С	D	Е	∮f
	7.5±0.1	7.5±0.1	16.0±0.3	7.0±0.1	1.75±0.1	1.5±0.1
SRH7045LF	Р	P1	P2	КО	Т	
	8.0±0.1	4.0±0.1	2.0±0.1	5.0±0.1	0.40±0.1	

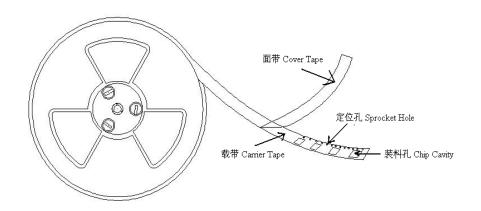
2)卷盘尺寸 REEL DIMENSION(mm)





Α	330±0.5
В	100±0.5
С	13.5±0.5
W	16.5±0.5

3) 卷盘包装示意图 Tape packing diagram

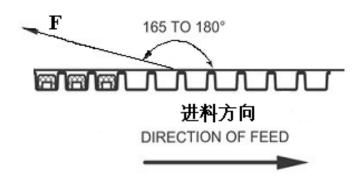


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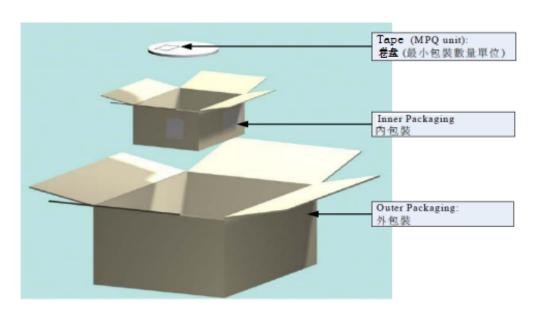
4)剥离强度要求Peeling required

①F 力大小: 20~100g;

②面带剥离角度: 165°~180°。



5) 包装数量 Packing quantity



项目 (Project)	数量(PCS)	尺寸规格(Size:mm)		
盘(Reel)	1000	13"		
内盒 (Inner box)	2000	340mm*340mm*65mm		
外箱 (Out box)	6000	360mm*360mm*225mm		

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YTEST METHOD									
L									
SPECIFICATION		TE	ST DETAILS						
△L/Lo≦±5%	The sam	The sample shall be soldered onto the printed circuit board							
	in figure	n figure 1 and a load applied unitil the figure in the arrow							
There shall be	direction	direction is made approximately 3mm.(keep time 30 seconds)							
no mechanical	PCB dim	ension shall the page 7/9							
damage or elec-	F(Pressurization)								
trical damege.									
			<i></i>						
		R5 / 15+2	15+2						
		45-6	4J±C	 -					
		10 20							
		PRESSURE ROD							
		figure-1		R340					
\^L/Lo≦±5%	The sam	ple shall be soldered onto	the printed c	ircuit board					
There shall be									
		·	,_,						
	(· · · · · · · ·								
New solder	Flux (ros	in, isopropyl alcohol{JIS-k	(-1522}) shall	be coated					
More than 90%	over the whole of the sample before hard, the sample shall								
	then be preheated for about 2 minutes in a temperature of								
	130~15	0°C and after it has been i	immersed to a	a depth 0.5mm					
	below for	3±0.2 seconds fully in me	olten solder M	1705 with					
	a temper	rature of 245±2°ℂ.							
	More than 90% of the electrode sections shall be couered								
	with new	solder smoothly when the	e sample is ta	aken out of					
	TEST METHOD L SPECIFICATION △L/Lo≤±5% There shall be no mechanical damage or electrical damege. △L/Lo≤±5% There shall be no mechanical damage.	SPECIFICATION △L/Lo≦±5% There shall be direction no mechanical damage or electrical damege. △L/Lo≦±5% The sam and when and a free no mechanical damage. New solder New solder New solder Nore than 90% Flux (ros then be publicated to the performance) SPECIFICATION The sam and when and a free no mechanical damage. Flux (ros then be publicated to the performance) SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage are specified to the second damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage. SPECIFICATION The sam in figure to the sam and when and a free no mechanical damage. SPECIFICATION The sam and when and a free no mechanical damage.	YTEST METHOD L SPECIFICATION □ L/Lo≤±5% The sample shall be soldered onto in figure 1 and a load applied unitil direction is made approximately 3r PCB dimension shall the page 7/9 PCB dimension shall the page 7/9 F(Pressurated damage or electrical damege. □ L/Lo≤±5% The sample shall be soldered onto and when a vibration having an arrand a frequency of from 10 to 55H be applied to the 3 directions (XY) (A total of 6 hours) New solder More than 90% Flux (rosin, isopropyl alcohol{JIS-k over the whole of the sample before then be preheated for about 2 minutage at the preheated for about 3 minutage at 3 minutage at the preheated for about 3 minutage at the preheate	TEST METHOD L SPECIFICATION △L/Lo≦±5% The sample shall be soldered onto the printed or in figure 1 and a load applied unitil the figure in the direction is made approximately 3mm. (keep time pCB dimension shall the page 7/9 F(Pressurization) F(Pressurization) There shall be pRESSURE ROD figure-1 There shall be and a frequency of from 10 to 55Hz/1 minute report be applied to the 3 directions (XY,Z) for 2 hours (A total of 6 hours) New solder More than 90% Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall over the whole of the sample before hard, the set then be preheated for about 2 minutes in a temp 130~150°C and after it has been immersed to a below for 3±0.2 seconds fully in molten solder Matemaps at temperature of 245±2°C. More than 90% of the electrode sections shall be specified and after it has been immersed to a below for 3±0.2 seconds fully in molten solder Matemaps at temperature of 245±2°C. More than 90% of the electrode sections shall be specified and after it has been immersed to a below for 3±0.2 seconds fully in molten solder Matemaps at temperature of 245±2°C. More than 90% of the electrode sections shall be specified and after it has been immersed to a below for 3±0.2 seconds fully in molten solder Matemaps at temperature of 245±2°C. More than 90% of the electrode sections shall be specified and after it has been immersed to a below for 3±0.2 seconds fully in molten solder Matemaps at the page 7/9 The sample shall be soldered onto the printed or in figure in the second printed of the sample before hard, the second printed of th	YTEST METHOD L SPECIFICATION △U/Lo≦±5% The sample shall be soldered onto the printed circuit board in figure 1 and a load applied unitil the figure in the arrow direction is made approximately 3mm. (keep time 30 seconds) PCB dimension shall the page 7/9 F(Pressurization) F(Pressurization) There shall be no mechanical damage. The sample shall be soldered onto the printed circuit board and when a vibration having an amplitude of 1.52mm and a frequency of from 10 to 55Hz/1 minute repeated should be applied to the 3 directions (XY,Z) for 2 hours each. (A total of 6 hours) New solder More than 90% Flux (rosin, isopropyl alcohol{UIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of 130~150°C and after it has been immersed to a depth 0.5mm below for 3±0.2 seconds fully in molten solder M705 with a temperature of 245±2°C.				

the solder bath.

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MECHANICAL									
TEST ITEM	SPECIFICATION								
Resistance to	There shall be	There shall be Temperature profile of reflow soldering							
Soldering heat	no damage or								
(reflow soldering)	problems.	Slow cooling (Stored at room temperature) The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.							
ELECTRICAL									
TEST ITEM	SPECIFICATION		TEST DETA	ILS					
Insulation resistance	There shall be no other damage or problems.	DC 100V voltage shall be a surface and the terminal. The insulation resistance sl							
Dielectric withstand	There shall be	AC 100V voltage shall be a surface and the terminal of		inute acrosset the	top				
voltage	damage or problems.		·						
Temperature	△L/L20°C ≦±10%	The test shall be performed	after the sam	nple has stabilized	in				
characteristics	0~2000 ppm/°C	an ambient temperature of - 40 to + 125℃, and the value							
	calculated based on the value applicable in a normal								
		temperature and narmal hui							

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ENVIROMEI	NT CHARA	CTERI	STIC	S					
TEST ITEM	SPECIFICATION								
High temperature	△L/Lo≦±5%	The sam	The sample shall be left for 500 hours in an atmospere with						
storage		a tempe	a temperature of 105±2℃ and a normal humidity.						
	There shall be	Upon co	Upon completion of the measurement shall be made after the						
	no mechanical	sample I	has bee	en left in a normal tempera	ature and normal				
	damage.	humidity	humidity for 1 hour.						
Low temperature	△L/Lo≦±5%	The sam	ple sha	all be left for 500 hours in	an atmosphere with				
storage		a tempe	rature c	of -40±3°ℂ .					
	There shall be	Upon co	mpletic	n of the test, the measure	ement shall be made				
	no mechanical	after the	sample	e has been left in a norma	l temperature and				
	damage.	normal h	numidity	for 1 hour.					
Change of	△L/Lo≦±5%	The sam	ple sha	all be subject to 5 continu	os cycles, such as shown				
temperature		in the tal	ble 2 be	elow and then it shall be s	subjected to standard				
	There shall be	stmosph	neric co	nditions for 1 hour, after w	which measurement				
	no other dama-	shall be	made.						
	ge of problems								
				tal	ble 2				
				Temperature	Duration				
			1	−40±3°C	10 min.				
				(Themostat No.1)					
			2	Standard	5 sec. or less				
				atmospheric	No.1→No.2				
			3	105±2℃	30 min.				
				(Themostat No.2)					
			4	Standard	5 sec. or less				
				atmospheric	No.2→No.1				
				,					
Moisuture storage	△L/Lo≦±5%	The sample shall be left for 500 hours in a temperature of							
		40±2 $^{\circ}$ C and a humidity(RH) of 90 $^{\circ}$ 95%.							
	There shall be	Upon completion of the test, the measurement shall be made							
	no mechanical	after the sample has been left in a normal temperature and							
	damage.	normal humidity more than 1 hour.							
Test conditions:									
The s	sample shall be ref	low soldere	ed onto	the printed circuit board i	n every test.				

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8、注意事项 Note

①本承认书保证我司产品作为一个单体时的质量情况。当我司产品被安装到贵司产品上时,请保证 贵司的产品已根据贵司的规范进行了有效评估和确认。

This product specification guarantees the quality of our product as a single unit. Please make sure that your product is evaluated and confirmed against your specifications when our product is mounted to your product.

②如果贵司对我司产品的使用已超过了本承认书所界定的产品功能,那么对于由此引发的失效, 我司将不予保证。

We cannot warrant against failure caused by any use of our product that deviates from the intended use as described in this product specification.

- ③为了保持终端电极的焊接性,并使包装材料保持良好状态,必须控制储存区的温度和湿度。 To maintain the solderabilty of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.
 - ※建议的条件: -10~+40℃, 30~70%RH。

Recommended conditions: $-10 \sim +40 \,^{\circ}\text{C}$, $30 \sim 70 \,^{\circ}\text{RH}$.

※储存超过六个月的,应在实际使用前进行焊接检验。
In case of storage over 6 months, soldrability shall be checked before actual usage.

※即使在理想的储存条件下,产品的可焊性也随着时间的推移而降低。因此,产品应从交货时算起, 建议8个月之内使用完。

Even under ideal storage conditions, the weldability of the product decreases over time. therefore, the product should be From the time of delivery, it is recommended that it be used within 8 months.

④本承认书在客户收到30天之内,必须签章返回,逾期视为默认。

The Specification Approval should be sent back to the supplier with customer's chop on it within 30 days after receiving it, or we will take it as approved by customer's automatically.

⑤如有特殊规格要求,请事前联络我司技术部人员。
In case of special specifications please contact our technical department prior staff.